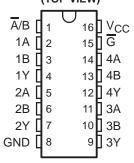
SCLS224B - DECEMBER 1982 - REVISED SEPTEMBER 2003

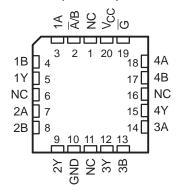
- Wide Operating Voltage Range of 2 V to 6 V
- **High-Current Inverting Outputs Drive Up To** 15 LSTTL Loads
- Low Power Consumption, 80-µA Max I_{CC}
- 'HC257 . . . Typical $t_{pd} = 9 \text{ ns}$

SN54HC257, SN54HC258...J PACKAGE SN74HC257, SN74HC258 . . . D, N, NS, OR PW PACKAGE (TOP VIEW)



- 'HC258 . . . Typical t_{pd} = 12 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- **Provides Bus Interface from Multiple** Sources in High-Performance Systems

SN54HC257, SN54HC258...FK PACKAGE (TOP VIEW)



NC - No internal connection

description/ordering information

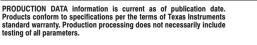
ORDERING INFORMATION

TA	PACK	AGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	DDID N	Tub (05	SN74HC257N	SN74HC257N
	PDIP – N	Tube of 25	SN74HC258N	SN74HC258N
		Tube of 40	SN74HC257D	
		Reel of 2500	SN74HC257DR	HC257
	SOIC - D	Reel of 250	SN74HC257DT	
		Tube of 40	SN74HC258D	110050
		Reel of 2500	SN74HC258DR	HC258
-40°C to 85°C	00D NO	D1 - (0000	SN74HC257NSR	HC257
	SOP – NS	Reel of 2000	SN74HC258NSR	HC258
		Tube of 90	SN74HC257PW	
		Reel of 2000	SN74HC257PWR	HC257
	T0000 514/	Reel of 250	SN74HC257PWT	
	TSSOP – PW	Tube of 90	SN74HC258PW	
		Reel of 2000	SN74HC258PWR	HC258
		Reel of 250	SN74HC258PWT	
	CDID I	Tube of OF	SNJ54HC257J	SNJ54HC257J
5500 to 40500	CDIP – J	Tube of 25	SNJ54HC258J	SNJ54HC258J
–55°C to 125°C	LCCC FK	Tubo of FF	SNJ54HC257FK	SNJ54HC257FK
	LCCC – FK	Tube of 55	SNJ54HC258FK	SNJ54HC258FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCLS224B - DECEMBER 1982 - REVISED SEPTEMBER 2003

description/ordering information (continued)

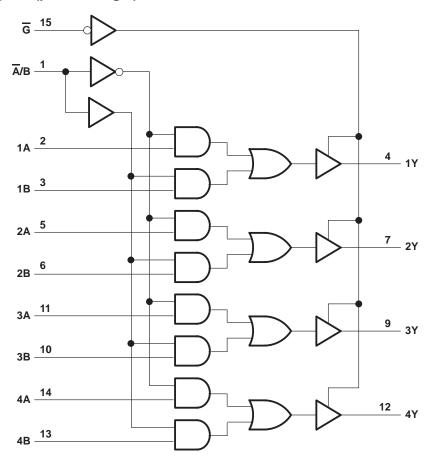
These devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable (\overline{G}) input is at a high logic level.

To ensure the high-impedance state during power up or power down, \overline{G} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

	INPL	JTS		OUTPUT Y				
G	A/B	Α	В	'HC257	'HC258			
Н	Χ	Χ	Χ	Z	Z			
L	L	L	X	L	Н			
L	L	Н	X	Н	L			
L	Н	Χ	L	L	Н			
L	Н	Χ	Н	Н	L			

'HC257 logic diagram (positive logic)

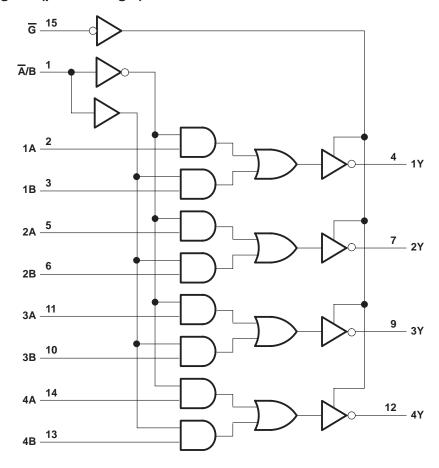


Pin numbers shown are for the D, J, N, NS, and PW packages.



SCLS224B - DECEMBER 1982 - REVISED SEPTEMBER 2003

'HC258 logic diagram (positive logic)



Pin numbers shown are for the D, J, N, NS, and PW packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)		±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CO}	c)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	- 	±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ_{JA} (see Note 1):	: D package	73°C/W
-	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T _{stg}		-65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



SCLS224B - DECEMBER 1982 - REVISED SEPTEMBER 2003

recommended operating conditions (see Note 2)

				154HC25 N54HC25			74HC25 174HC25	•	UNIT
			MIN	NOM	MAX	MIN NOM MA		MAX	
VCC	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
\vee_{IH}	High-level input voltage	V _{CC} = 4.5 V	3.15			3.15			V
		VCC = 6 V	4.2			4.2			
		V _{CC} = 2 V			0.3			0.5	
٧ _{IL}	Low-level input voltage	$V_{CC} = 4.5 \text{ V}$			0.9			1.35	V
		VCC = 6 V			1.2			1.8	
٧ _I	Input voltage		0		VCC	0		Vcc	V
٧o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
Δt/Δν	Input transition rise/fall time	V _{CC} = 4.5 V			500			500	ns
		VCC = 6 V			400	_		400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	ONDITIONS	VCC	Т	A = 25°C	;	SN54H SN54H		SN74HC257, SN74HC258		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Vон	$V_I = V_{IH}$ or V_{IL}		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -7.8 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
		ΙΟL = 20 μΑ	4.5 V		0.001	0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.001	0.1		0.1		0.1	V
		I _{OL} = 6 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 7.8 mA	6 V		0.15	0.26		0.4		0.33	
IJ	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0	•	6 V		±0.01	±0.5		±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	I _O = 0	6 V			8		160		80	μΑ
C _i			2 V to 6 V		3	10		10		10	pF

SCLS224B - DECEMBER 1982 - REVISED SEPTEMBER 2003

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

	FROM	то	.,	T,	ղ = 25°C	;	SN54H	C257	SN74H	C257	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		50	100		150		125	
	A or B	Any Y	4.5 V		10	20		30		25	
			6 V		9	17		25		21	
^t pd			2 V		50	100		150		125	ns
	Ā/B	Any Y	4.5 V		10	20		30		25	
			6 V		9	17		25		21	
			2 V		75	150		225		190	
^t en	G	Any Y	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
			2 V		75	150		225		190	
^t dis	G	Any Y	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
			2 V		28	60		90		75	
t _t		Any Y	4.5 V		8	12		18		15	ns
			6 V		6	10		15		13	

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

	FROM	то		T,	Δ = 25°C	;	SN54H	C257	SN74H	C257		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V		75	150		245		190		
	A or B	Any Y	4.5 V		15	30		45		38		
			6 V		13	26		38		32		
^t pd			2 V		75	150		245		190	ns	
	Ā/B	Any Y	Any Y	4.5 V		15	30		45		38	
			6 V		13	26		38		32		
			2 V		100	200		300		250		
t _{en}	G	Any Y	4.5 V		24	40		60		50	ns	
			6 V		18	34		51		43		
			2 V		45	210		315		265		
t _t		Any Y	4.5 V		17	42		63		53	ns	
			6 V		13	36		53		45		

SCLS224B - DECEMBER 1982 - REVISED SEPTEMBER 2003

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

242445	FROM	то	.,	T	λ = 25°C	;	SN54H	C258	SN74H	C258	
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		60	100		150		125	
	A or B	Any Y	4.5 V		13	20		30		25	
			6 V		12	17		25		21	
^t pd			2 V		60	115		175		145	ns
	Ā/B	Any Y	4.5 V		13	23		35		29	
			6 V		12	20		30		25	
			2 V		70	150		225		190	
^t en	G	Any Y	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
			2 V		75	150		225		190	
^t dis	G	Any Y	4.5 V		15	30		45		38	ns
			6 V		13	26		38		32	
			2 V		28	60		90		75	
t _t		Any Y	4.5 V		8	12		18		15	ns
			6 V	_	6	10	_	15		13	

switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

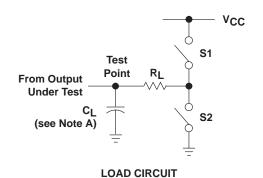
242445	FROM	то	l .,	T,	\ = 25°C	;	SN54H	IC258	SN74H	C258						
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT					
			2 V		95	150		245		190						
	A or B	Any Y	4.5 V		23	30		45		38						
,			6 V		21	26		38		32						
^t pd			2 V		95	165		240		210	ns					
	Ā/B	Any Y	Any Y	Any Y	Any Y	Any Y	4.5 V		23	33		48		42		
			6 V		21	28		41		36						
			2 V		100	200		300		250						
t _{en}	G	Any Y	4.5 V		24	40		60		50	ns					
			6 V		18	34		51		43						
			2 V		45	210		315		265						
t _t			Any Y	Any Y	Any Y	Any Y	Any Y	4.5 V		17	42		63		53	ns
			6 V		13	36	_	53		45						

operating characteristics, T_A = 25°C

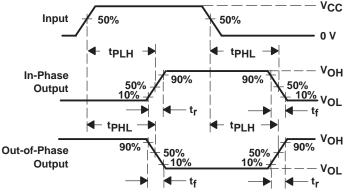
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per multiplexer	No load	40	pF

SCLS224B - DECEMBER 1982 - REVISED SEPTEMBER 2003

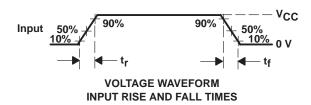
PARAMETER MEASUREMENT INFORMATION

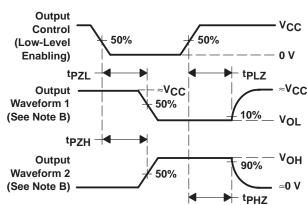


PARAI	METER	RL	CL	S1	S2
	tPZH	1 k Ω	50 pF or	Open	Closed
^t en	tPZL	1 K22	150 pF	Closed	Open
4	tPHZ	1 k Ω	50 pF	Open	Closed
^t dis	tPLZ	1 K22	30 pr	Closed	Open
t _{pd} or t _t			50 pF or 150 pF	Open	Open



VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT TRANSITION TIMES





VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and test-fixture capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
 - D. The outputs are measured one at a time with one input transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



www.ti.com

9-Jun-2025

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
85124012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	85124012A SNJ54HC 257FK
8512401EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512401EA SNJ54HC257J
SN54HC257J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC257J
SN54HC257J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC257J
SN74HC257D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC257
SN74HC257DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC257
SN74HC257DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC257
SN74HC257DRG4.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC257
SN74HC257DT	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC257
SN74HC257N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC257N
SN74HC257N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC257N
SN74HC257NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC257
SN74HC257NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC257
SN74HC257PW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC257
SN74HC257PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU SN NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC257
SN74HC257PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC257
SN74HC258D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC258
SN74HC258DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258
SN74HC258DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258
SN74HC258N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC258N
SN74HC258N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC258N
SN74HC258NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258
SN74HC258NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258
SN74HC258PW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC258
SN74HC258PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258
SN74HC258PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC258



www.ti.com

9-Jun-2025

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54HC257FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	85124012A SNJ54HC 257FK
SNJ54HC257FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	85124012A SNJ54HC 257FK
SNJ54HC257J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512401EA SNJ54HC257J
SNJ54HC257J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8512401EA SNJ54HC257J

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE OPTION ADDENDUM

www.ti.com 9-Jun-2025

OTHER QUALIFIED VERSIONS OF SN54HC257, SN74HC257:

Catalog: SN74HC257

• Military : SN54HC257

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



www.ti.com 23-May-2025

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC257DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC257NSR	SOP	NS	16	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74HC257NSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC257PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC257PWR	TSSOP	PW	16	2000	330.0	12.4	6.85	5.45	1.6	8.0	12.0	Q1
SN74HC258DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC258NSR	SOP	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC258PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



www.ti.com 23-May-2025



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC257DR	SOIC	D	16	2500	356.0	356.0	35.0
SN74HC257NSR	SOP	NS	16	2000	356.0	356.0	35.0
SN74HC257NSR	SOP	NS	16	2000	356.0	356.0	35.0
SN74HC257PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
SN74HC257PWR	TSSOP	PW	16	2000	366.0	364.0	50.0
SN74HC258DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74HC258NSR	SOP	NS	16	2000	356.0	356.0	35.0
SN74HC258PWR	TSSOP	PW	16	2000	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

www.ti.com 23-May-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
85124012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74HC257N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC257N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC257N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC257N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC258N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC258N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC258N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC258N.A	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54HC257FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC257FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



INSTRUMENTS www.ti.com

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2025. Texas Instruments Incorporated